

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Hidemitsu Aoki, et al.

**Examiner:** S. T. Chaudhry

**Serial No.:** ~~unassigned~~ 10/07SS66

**Art Unit:** 1746

**Filed:** ~~herewith~~ 2-13-02

**Docket:** 12688A

**For:** METHOD FOR CLEANING  
SEMICONDUCTOR WAFER AFTER  
CHEMICAL MECHANICAL POLISHING  
COPPER WIRING

**Dated:** February 13, 2002

Assistant Commissioner for Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Applicants submit the following Amendment for entry in the above-identified application.

---

**CERTIFICATE OF MAILING BY EXPRESS MAIL**

**Express Mail Mailing Label Number** EV-010-535-685-US

**Date of Deposit:** February 13, 2002

I hereby certify that this correspondence is being deposited with the United States Postal Service Express Mail Post Office to Addressee service under 37 C.F.R. §1.10 on the date indicated above and is addressed to the Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231.

**Dated:** February 13, 2002

  
Michelle Mustafa